

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Byung-Choon LEE</td> <td>10/28/2009</td> </tr> <tr> <td>Doo-Han HA</td> <td>10/28/2009</td> </tr> <tr> <td>Tae-Uk KIM</td> <td>10/28/2009</td> </tr> <tr> <td>Jae-Hoon JEONG</td> <td>10/28/2009</td> </tr> <tr> <td>Il-Jin KIM</td> <td>10/28/2009</td> </tr> </tbody> </table>		Name	Execution Date	Byung-Choon LEE	10/28/2009	Doo-Han HA	10/28/2009	Tae-Uk KIM	10/28/2009	Jae-Hoon JEONG	10/28/2009	Il-Jin KIM	10/28/2009
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RECEIVING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Cheil Industries Inc.</td> </tr> <tr> <td>Street Address:</td> <td>290 Gongdan-dong</td> </tr> <tr> <td>Internal Address:</td> <td>Gumi-si</td> </tr> <tr> <td>City:</td> <td>Gyeongsangbuk-do</td> </tr> <tr> <td>State/Country:</td> <td>REPUBLIC OF KOREA</td> </tr> <tr> <td>Postal Code:</td> <td>730-710</td> </tr> </table>		Name:	Cheil Industries Inc.	Street Address:	290 Gongdan-dong	Internal Address:	Gumi-si	City:	Gyeongsangbuk-do	State/Country:	REPUBLIC OF KOREA	Postal Code:	730-710
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CORRESPONDENCE DATA													
<p>Fax Number: (704)945-6735 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 704-945-6700 Email: rowens@summalaw.com</p> <p>Correspondent Name: Melissa B. Pendleton Address Line 1: 11610 N. Community House Road Address Line 2: Suite 200 Address Line 4: Charlotte, NORTH CAROLINA 28277</p>													
ATTORNEY DOCKET NUMBER:	7020.041												

OP \$40.00 12612735

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**PATENT
 REEL: 023474 FRAME: 0287**

NAME OF SUBMITTER:

Melissa B. Pendleton

Total Attachments: 4

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RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Byung-Choon LEE
Doo-Han HA
Tae-Uk KIM
Jae-Hoon JEONG
Il-Jin KIM

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) October 28, 2009

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Cheil Industries, Inc.

Internal Address: _____

Street Address: 290, Gongdan 2-dong,
Gumi-si,

City: Gyeongsangbuk-do

State: _____

Country: Korea

Zip: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

12/612,735

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Summa, Additon & Ashe, P.A.

Internal Address: _____

Street Address: 11610 N. Community House
Road, Suite 200

City: Charlotte

State: NC

Zip: 28277-2199

Phone Number: 704-945-6700

Fax Number: 704-945-6735

Email Address: mpendleton@summalaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 50-0332

Authorized User Name Melissa B. Pendleton

9. Signature: /Melissa B. Pendleton/

November 5, 2009

Signature

Date

Melissa B. Pendleton

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

ASSIGNMENT

WHEREAS, I, **Byung-Choon LEE**, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; **Doo-Han HA**, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; **Tae-Uk KIM**, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 62 Pyeongyeo-Dong, Yeosu-si, Jeollanam-do, Republic of Korea; **Jae-Hoon JEONG**, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 62 Pyeongyeo-Dong, Yeosu-si, Jeollanam-do, Republic of Korea; and **Il-Jin KIM**, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 62 Pyeongyeo-Dong, Yeosu-si, Jeollanam-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition and Molded Product Made Using the Same*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from Korean Application No. 10-2008-0109848, filed November 6, 2008, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation, having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, (hereinafter referred to as "ASSIGNEE") has acquired the equitable right, title, and interest—and is desirous of

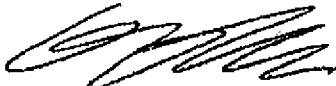
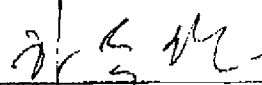



acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

<u>10.28</u> , 2009	 Byung-Choon LEE
<u>28 Oct</u> , 2009	 Doo-Han HA
<u>28. Oct.</u> , 2009	 Tae-Uk KIM
<u>10.28</u> , 2009	 Jae-Hoon JEONG
<u>10.28</u> , 2009	 Il-Jin KIM

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